## Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP x360 310 G1

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screw Driver</td>
</tr>
<tr>
<td>Description #2</td>
<td>No.0</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove Rubber Foot
2. remove low door
3. remove Battery module
4. remove HDD module
5. remove LCD module
6. remove MB
7. remove speaker module
8. remove K/B module
9. remove T/P module
10. remove I/O board
11. divide Display assy (remove hinge cap TOP)
12. divide Display assy (remove hinge cap BTN)
13. divide Display assy (remove LCD cover)
14. divide Display assy (remove Hinge)
15. divide Display assy (remove LVDS Cable)
16. divide Display assy (Antenna cable)
17. divide Display assy (sensor board)
18. divide Display assy (remove Camera)
19. divide Display assy (remove Panel)
20. divide Display assy (remove LCD brkt)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove rubber foot
Step 2 Remove log low

Step 3 Remove Battery module
Step 4 Remove Hdd module

Step 5 Remove LCD module
Step 6 Remove M/B
Step 7 Remove speaker module.

Step 8 Remove K/B

Step 9 Remove T/P module

Step 10 Remove I/O board

Step 11 Remove Hinge cap top

Step 12 Remove Hinge cap BTN
Step 13 Remove LCD Cover

Step 14 Remove Hinge

Step 15 Remove LVDS & sensor cable

Step 16 Remove Antenna cable

Step 17 Remove sensor board

Step 18 Remove camera module
Step 19 Remove Panel

Step 20 Remove LCD Brkt